<table>
<thead>
<tr>
<th>System Specifications</th>
<th>Orbotech Diamond 10</th>
<th>Orbotech Diamond 10XL</th>
</tr>
</thead>
<tbody>
<tr>
<td>Minimum SRO *</td>
<td>75μm</td>
<td></td>
</tr>
<tr>
<td>Minimum Dam Size *</td>
<td>50μm</td>
<td></td>
</tr>
<tr>
<td>Registration Accuracy **</td>
<td>±10μm</td>
<td></td>
</tr>
<tr>
<td>Max. Panel Area (X/Y)</td>
<td>25” x 26” (635mm x 660mm)</td>
<td>25” x 32” (635mm x 812mm)</td>
</tr>
<tr>
<td>Max. Panel Area (X/Y)</td>
<td>24.5”x23” (622mm x 584mm)</td>
<td>24.5”x30” (622mm x 762mm)</td>
</tr>
<tr>
<td>Max. Exposure Area (X/Y)</td>
<td>24.5” x 26” (622mm x 660mm)</td>
<td>24.5” x 32” (622mm x 812mm)</td>
</tr>
<tr>
<td>Max. Exposure Area (X/Y)</td>
<td>24”x22.5” (609mm x 571mm)</td>
<td>24”x29.5” (609mm x 749mm)</td>
</tr>
<tr>
<td>Max. Panel Area (X/Y)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Max. Exposure Area (X/Y)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Exposures Energy Range</td>
<td>50-2,200 mJ/cm²</td>
<td></td>
</tr>
<tr>
<td>Dimensions</td>
<td>Height: 1,960mm</td>
<td>Height: 1,960mm</td>
</tr>
<tr>
<td></td>
<td>Depth: 3,226mm</td>
<td>Depth: 3,315mm</td>
</tr>
<tr>
<td></td>
<td>Width: 1,900mm</td>
<td>Width: 1,900mm</td>
</tr>
<tr>
<td>Weight</td>
<td>5,000Kg</td>
<td></td>
</tr>
<tr>
<td>Clamping</td>
<td>Optional</td>
<td></td>
</tr>
<tr>
<td>Application</td>
<td>Solder mask exposure</td>
<td></td>
</tr>
</tbody>
</table>

* Dependent on solder resist type and process
** All values are 30
- The above specifications are subject to change without notification.
Orbotech Diamond 10/10XL is an advanced high-capacity digital imaging (DI) solution for a wide variety of solder mask (SM) applications, including HDI, MLB and FPCB. Powered by Orbotech’s proprietary SolderFast Technology™, the field-proven Orbotech Diamond 10/10XL delivers high-quality imaging and fast throughput for the most complex designs. Raising the DI bar for solder mask applications, Orbotech Diamond 10/10XL is a high-end mass production solution that enhances imaging accuracy while decreasing total cost of ownership (TCO).

Benefits

High-Quality Imaging and High Throughput
- Patented, high power illumination source
- 3-wavelength spectrum for high-quality sidewalls, minimal undercuts and excellent surface quality
- “One Pass” technology to cover full panel area at one imaging with uniform imaging of the entire panel area
- On the fly target recognition and acquisition capabilities
- High depth of focus (DOF) for challenging topographies
- Adaptable for a wide variety of customer processes, eliminating the need to qualify new materials

High Capacity
- Fast and easy SM imaging set-up for new jobs
- Dual-table transport mechanism for optimal imaging time and efficiency
- Optional clamping solution
- Industry 4.0 and automation-ready solution

Outstanding Imaging Accuracy
- Registration accuracy as fine as ±10µm
- Advanced scaling modes and algorithms for challenging panel distortions

Low Total Cost of Ownership
- High production system efficiency
- Long-life LEDs
- Low power consumption

High Quality Imaging and High Throughput

High Capacity Mass Production Solution

Outstanding Imaging Accuracy

Advanced Scaling modes and algorithms for challenging panel distortions include Auto Scaling, Partial Scaling and Non Linear Scaling
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**High Quality Imaging and High Throughput**

- 26" Table Movement Direction
- 24.5" Table Movement Direction

**High Capacity Mass Production Solution**

- Automation ready solution
- Clamping
- Advanced Scaling modes and algorithms for challenging panel distortions include Auto Scaling, Partial Scaling and Non Linear Scaling

**Outstanding Imaging Accuracy**

- High registration accuracy
- 365nm, 385nm, 405nm spectrum for high-quality sidewalls, minimal undercut and excellent surface quality
- High Depth of Focus (DOF) for challenging topographies
- On-The-Fly target recognition and acquisition